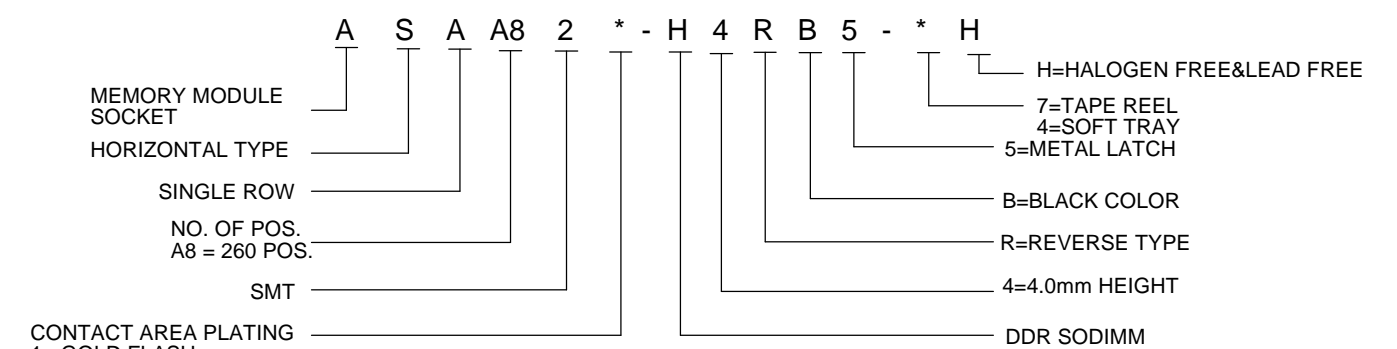
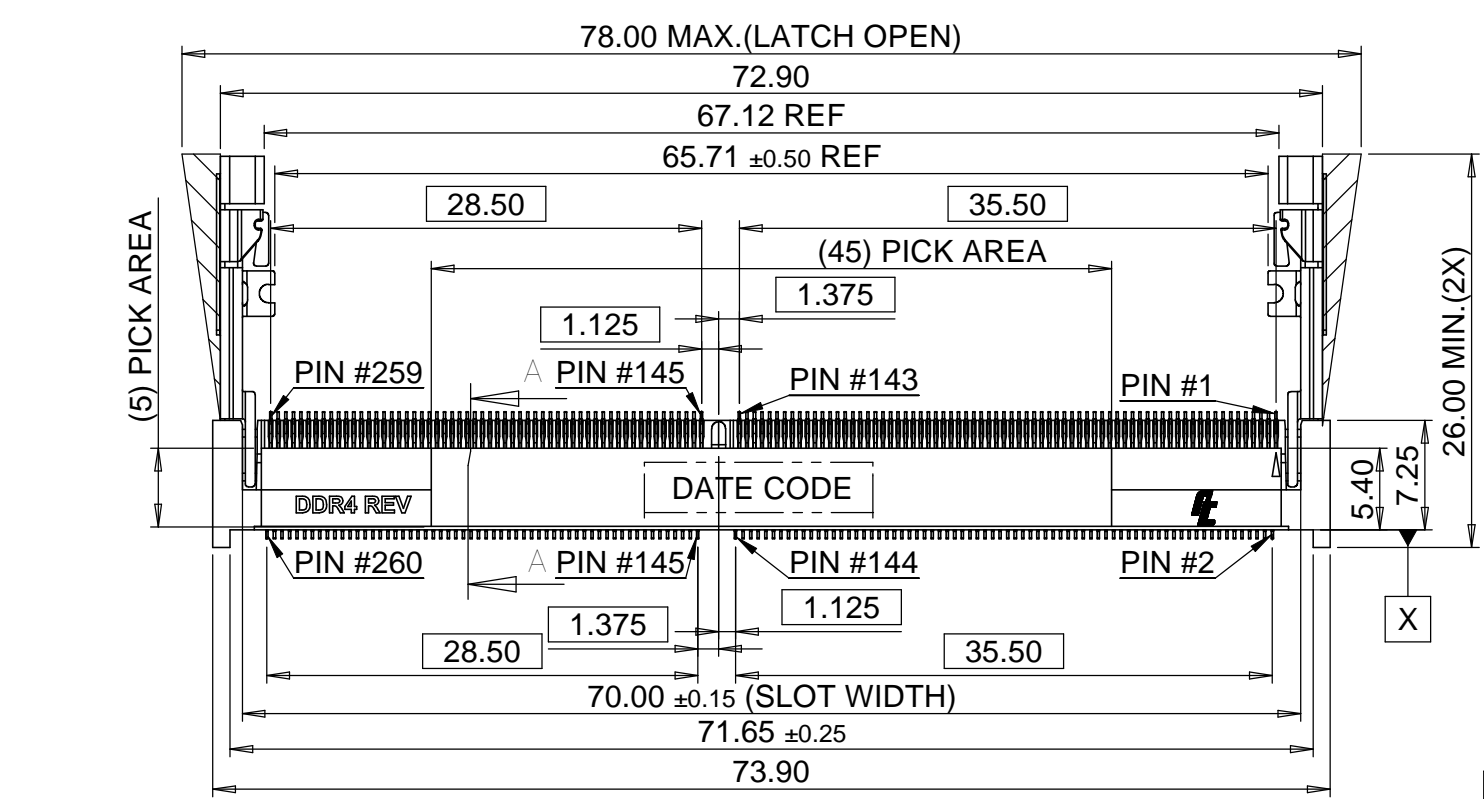
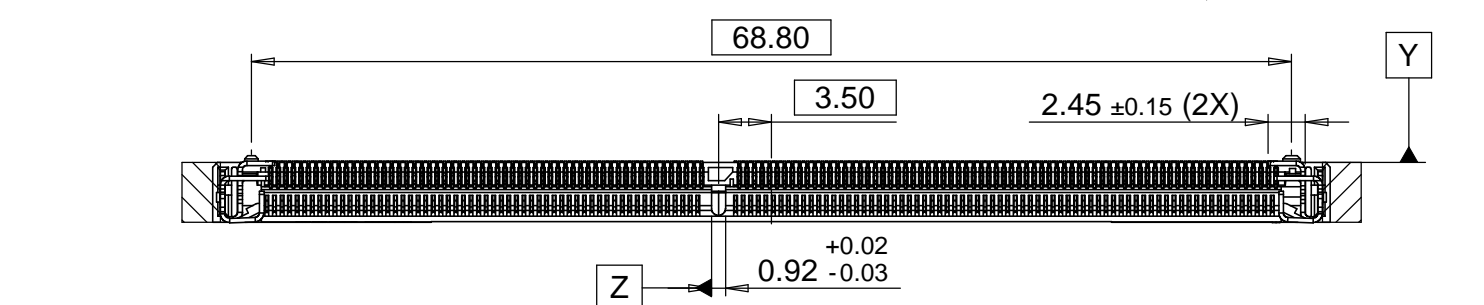
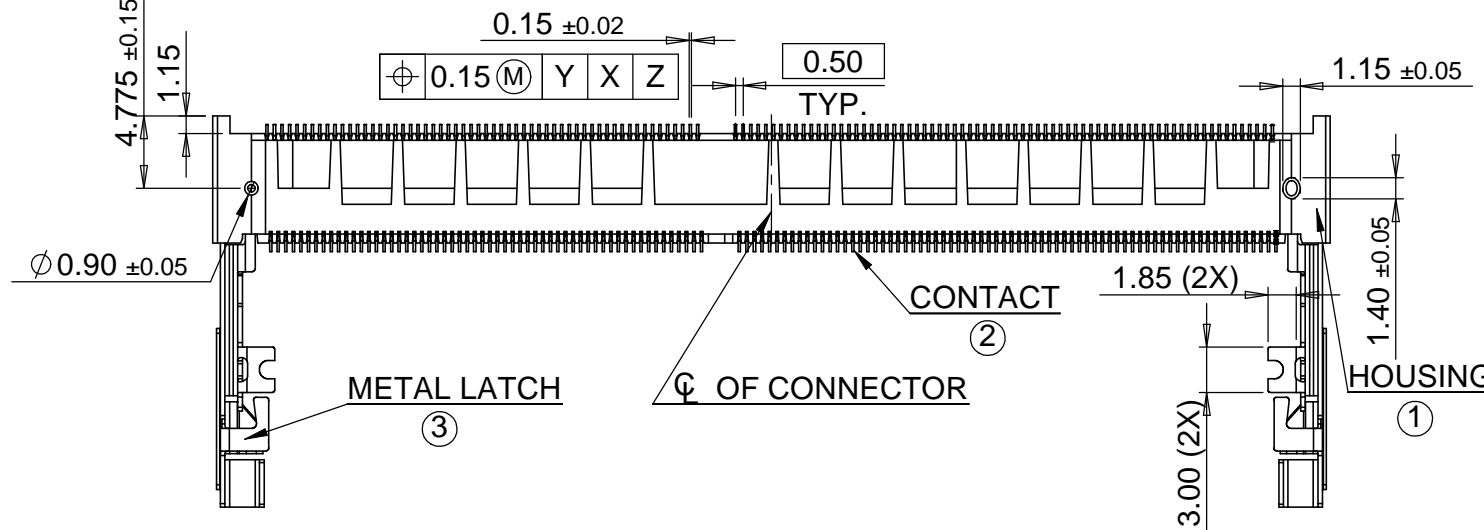


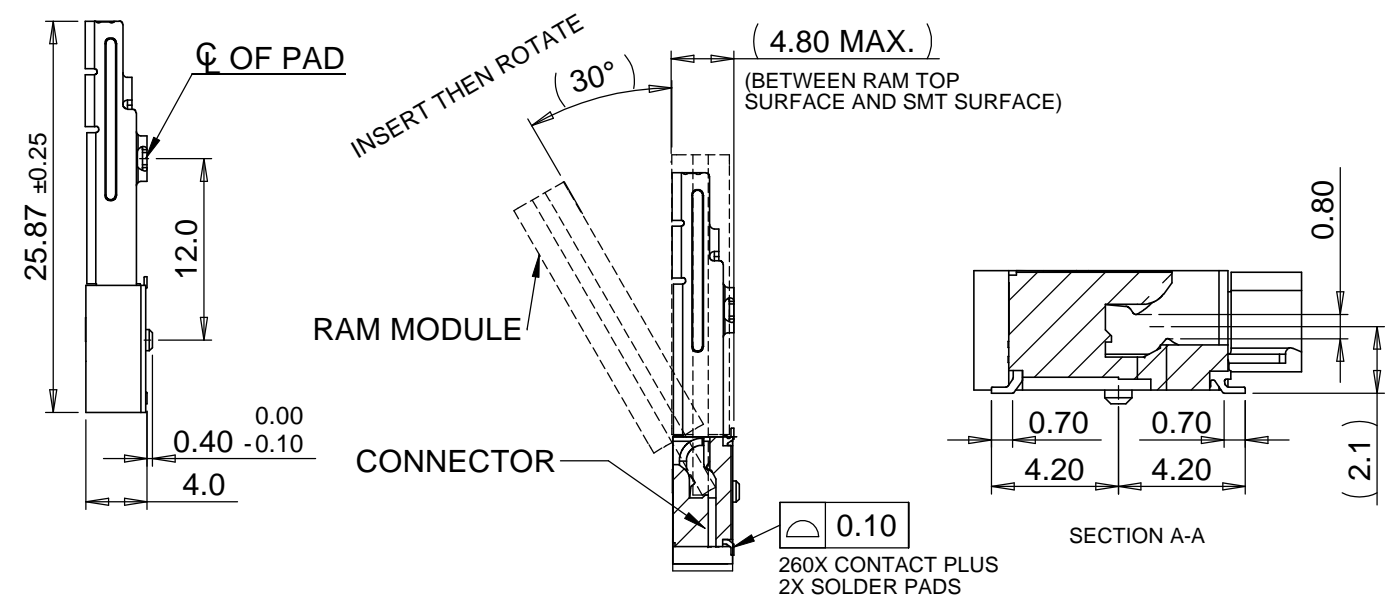
SOLIDWORKS GENERATED DRAWING, DO NOT CHANGE BY HAND

REV.	ECN. NO.	APPD.
A	BC-17-0040894	Davy Bu
B	BC-18-0016297	Davy Bu

- NOTES:
- ELECTRICAL CHARACTERISTICS:
    - CONTACT CURRENT RATING: 0.5 AMPERE MAX. PER PIN.
    - VOLTAGE RATING: 1.2V DC.
    - INSULATION RESISTANCE: 100 MEGAOHMS MIN. AT 500V DC.
    - DIELECTRIC WITHSTANDING VOLTAGE: 250V AC RMS AT 60Hz, FOR 1 MINUTE.
    - CONTACT RESISTANCE: 60 MILLIOHMS MAX. PER PIN INITIAL  
 $\Delta$ 10 MILLIOHMS PER PIN AFTER FULL ENVIRONMENTAL TESTING.
  - MECHANICAL CHARACTERISTICS: DURABILITY: 25 MATING CYCLES.
  - OPERATION TEMPERATURE: -55 °C TO +85 °C.
  - RECOMMENDED PROCESS CONDITION: SMT, PEAK TEMPERATURE: 260 °C 10~20S.
  - PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAILS & AVAILABILITY.



- CONTACT AREA PLATING
- 1= GOLD FLASH
  - Y= 5u" GOLD PLATING
  - 6= 10u" GOLD PLATING
  - 7= 15u" GOLD PLATING
  - 3= 30u" GOLD PLATING

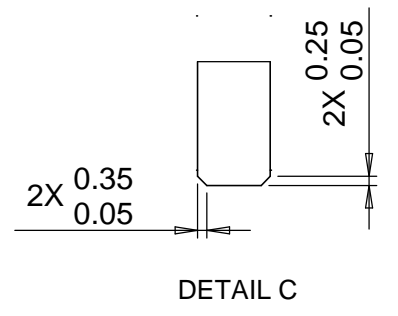
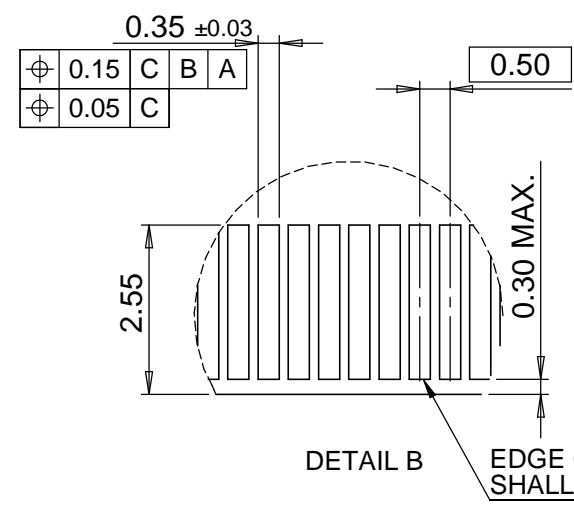
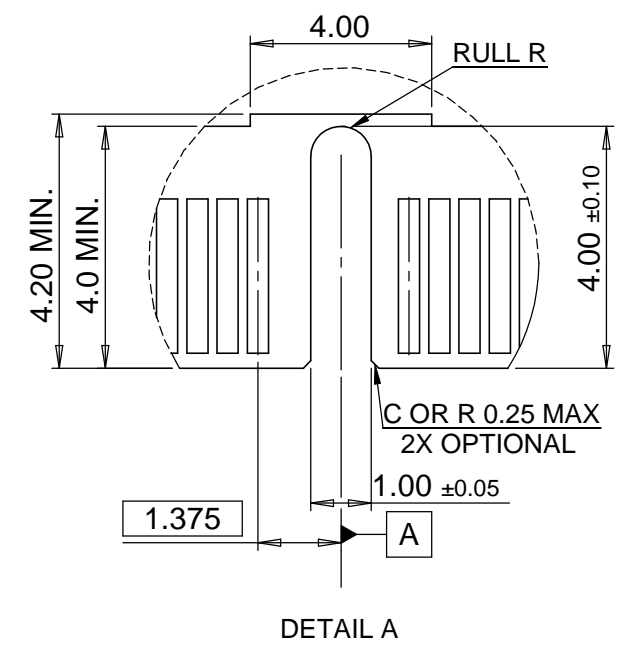
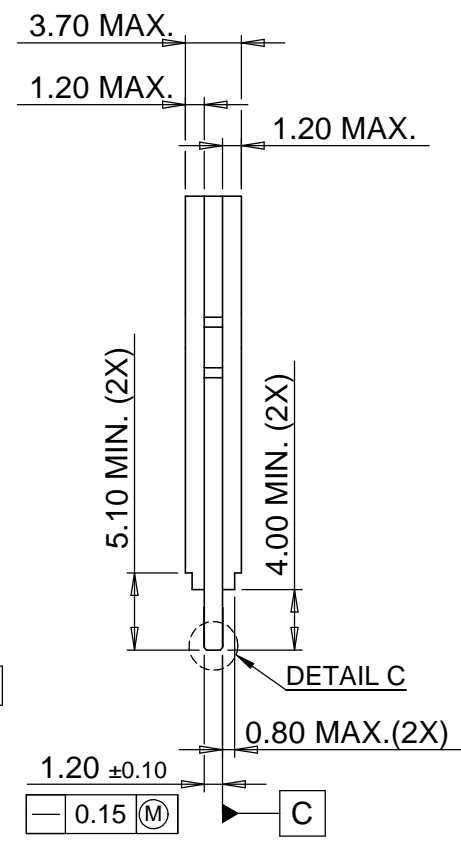
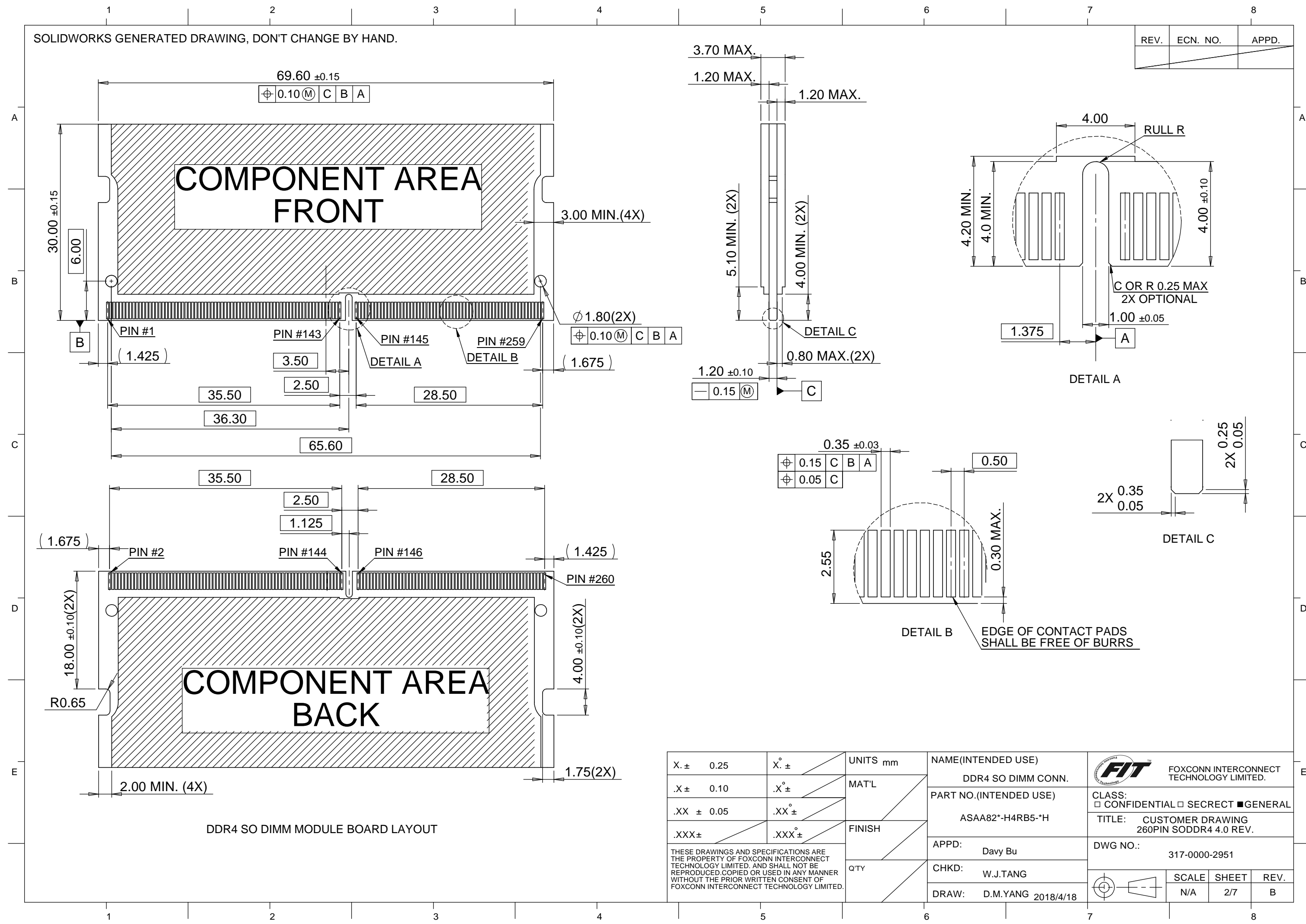


ITEM	DESCRIPTION	QTY	MATERIAL	TREATMENT
3	METAL LATCH	2	STAINLESS STEEL	10u" NICKEL UNDER PLATING 2u" Pd PLATING AT SOLDER PAD AREA.
2	CONTACT	260	PHOSPHOR BRONZE C5210	50u" NICKEL UNDER PLATING GOLD FLASH OR 5u" OR 10u" GOLD PLATING AT CONTACT AREA GOLD FLASH PLATING AT TAIL 90u" NICKEL UNDER PLATING 15u" OR 30u" GOLD PLATING AT CONTACT AREA GOLD FLASH PLATING AT TAIL
1	HOUSING	1	LCP	UL94V-0, HALOGEN FREE, BLACK COLOR

X. ± 0.30	X. °	UNITS mm	NAME (INTENDED USE)	FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X ± 0.25	.X °	MAT'L	DDR4 SO DIMM CONN.	
.XX ± 0.15	.XX °	FINISH	PART NO. (INTENDED USE)	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
.XXX ±	.XXX °		ASAA82*-H4RB5*-H	TITLE: CUSTOMER DRAWING 260PIN SODDDR4 4.0 REV.
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			CHKD: W.J.TANG	SCALE SHEET REV.
			DRAW: D.M.YANG 2018/4/25	N/A 1/7 B

SOLIDWORKS GENERATED DRAWING, DON'T CHANGE BY HAND.

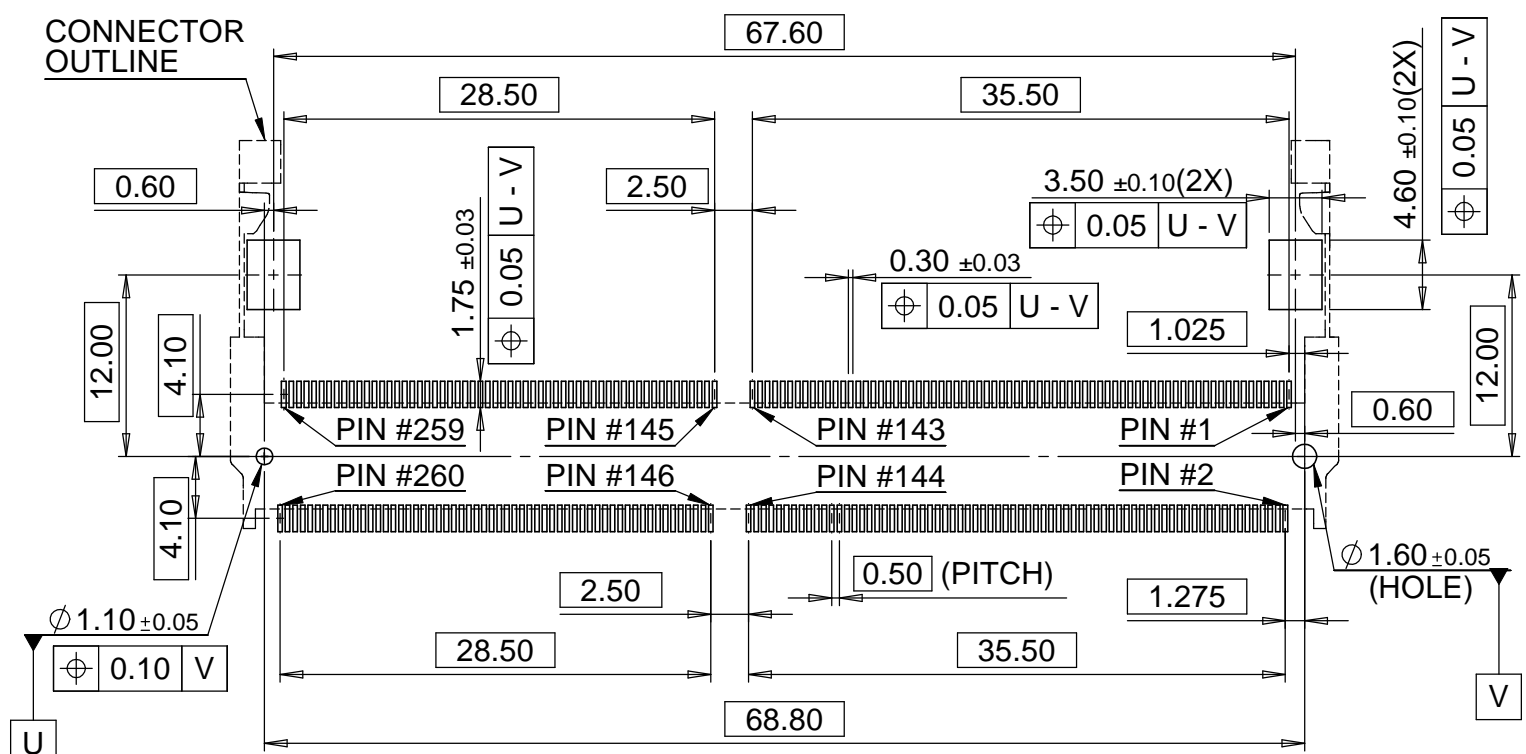
REV.	ECN. NO.	APPD.



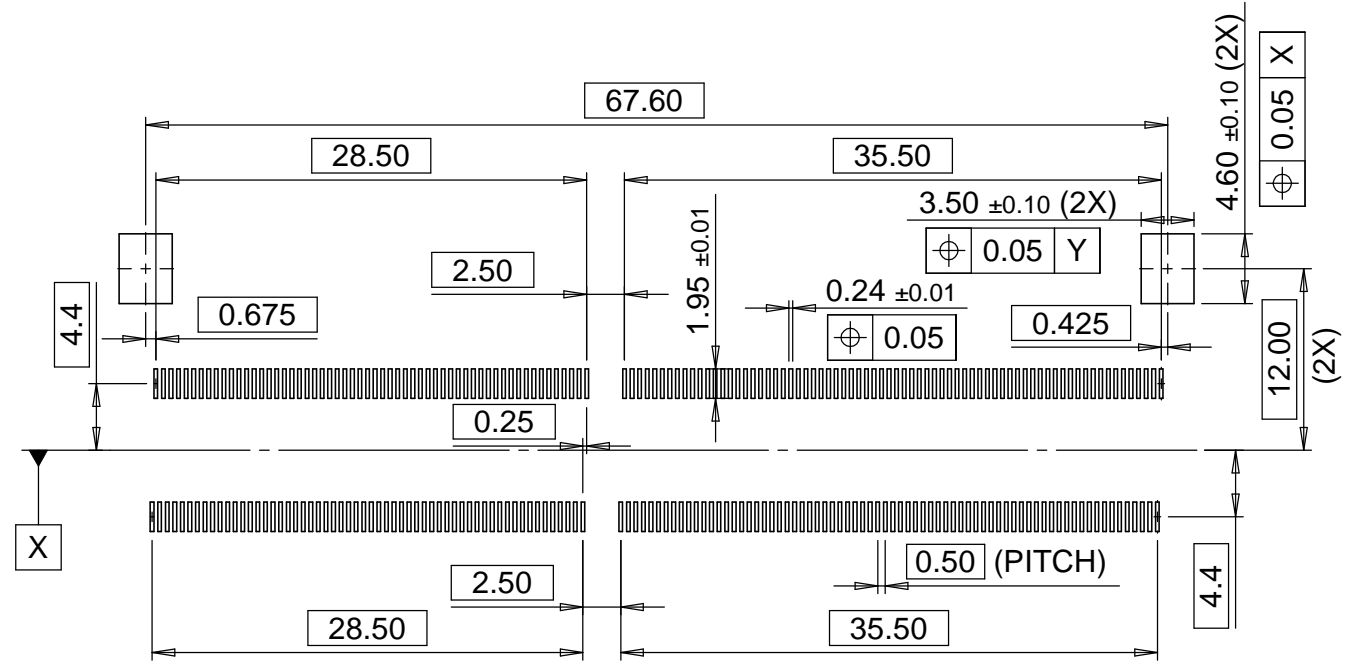
DDR4 SO DIMM MODULE BOARD LAYOUT

X. ± 0.25	X. ° ±	UNITS mm	NAME (INTENDED USE) DDR4 SO DIMM CONN.	FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X ± 0.10	.X ° ±			
.XX ± 0.05	.XX ° ±	FINISH	PART NO. (INTENDED USE) ASAA82*-H4RB5-*H	TITLE: CUSTOMER DRAWING 260PIN SODDDR4 4.0 REV.
.XXX ±	.XXX ° ±			QTY
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED, AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.			CHKD: W.J.TANG	SCALE SHEET REV. N/A 2/7 B
			DRAW: D.M.YANG 2018/4/18	

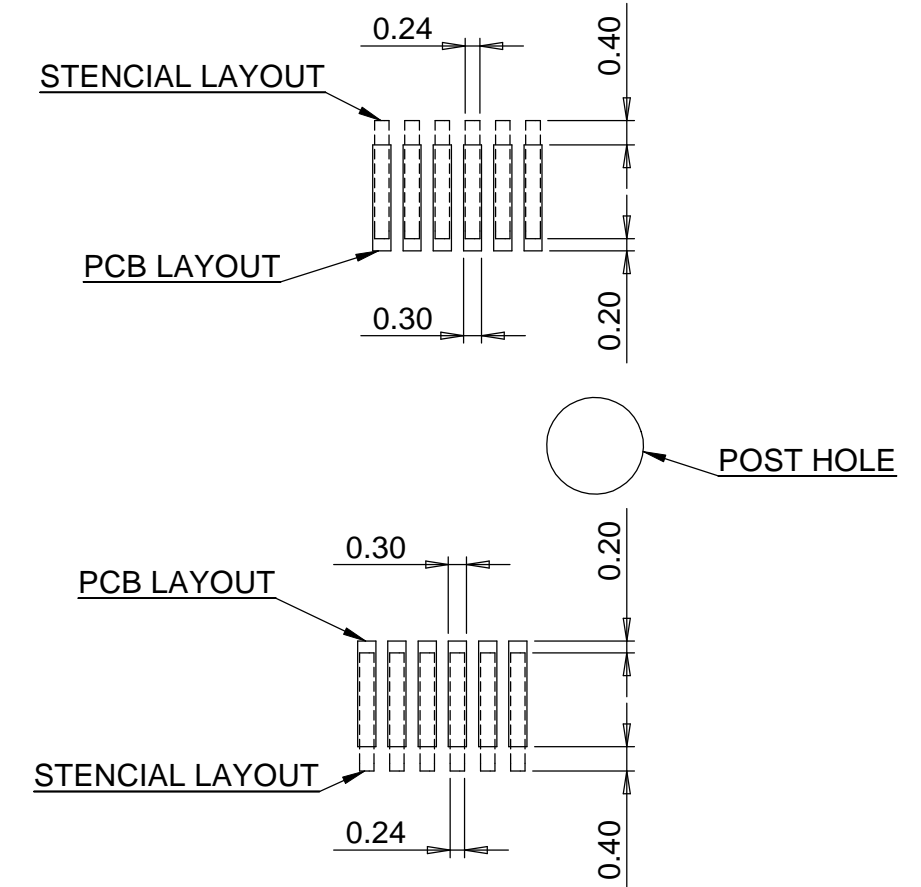
REV.	ECN. NO.	APPD.




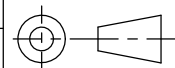
P.C.B. LAYOUT (RECOMMEND THICKNESS=1.40MM)  
DATUM Z IS THE PCB SOLDER SURFACE



STENCIL LAYOUT (RECOMMEND THICKNESS=0.15MM)  
DATUM Z IS THE PCB SOLDER SURFACE

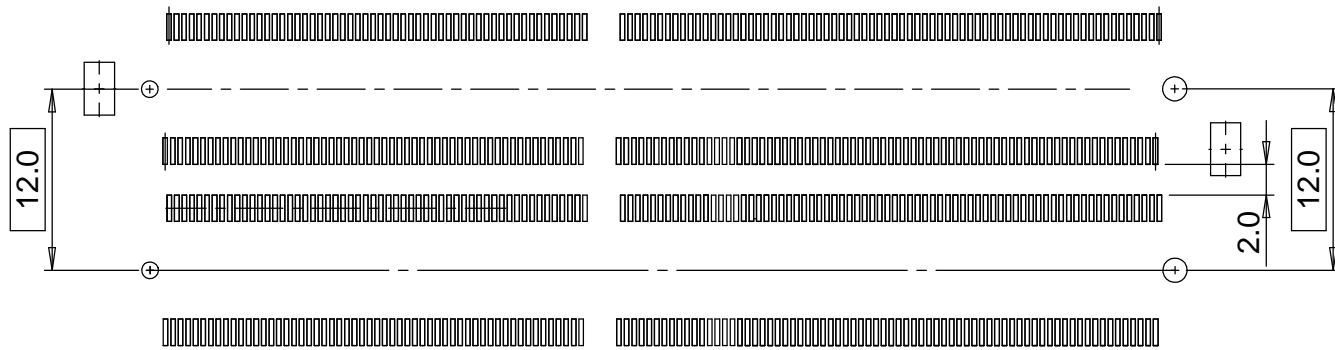
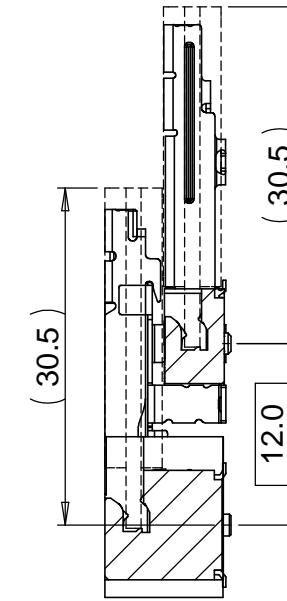
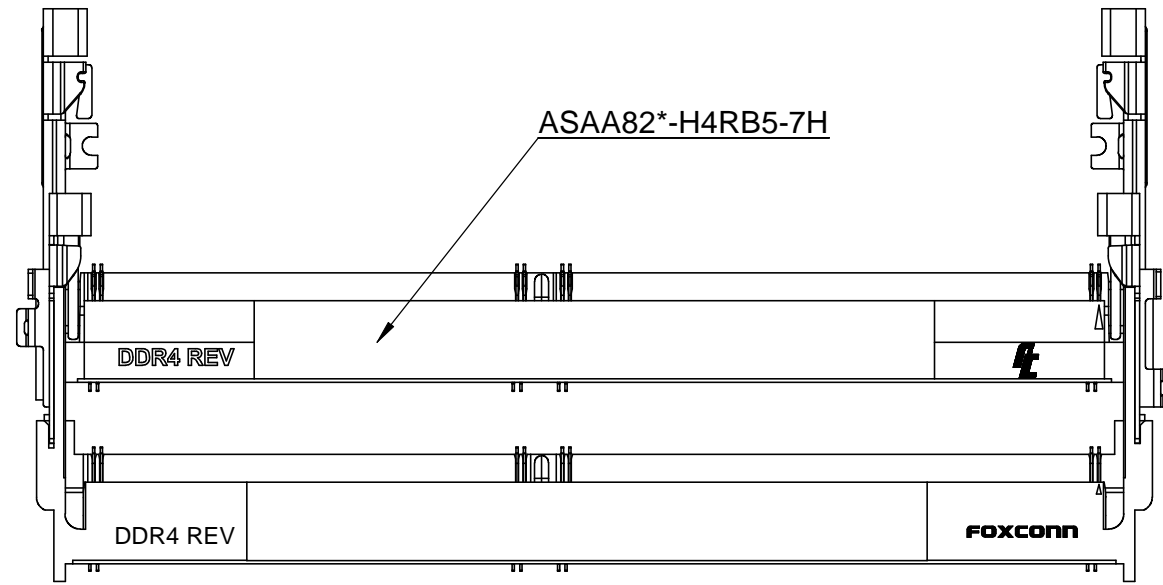


STACKED BY PCB LAYOUT AND STENCIL LAYOUT


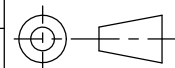
X. ± 0.25	X. ° ±	UNITS mm	NAME (INTENDED USE)	 FOXCONN INTERCONNECT TECHNOLOGY LIMITED.	
.X ± 0.10	.X ° ±		DDR4 SO DIMM CONN.		
.XX ± 0.05	.XX ° ±	MAT'L	PART NO. (INTENDED USE)	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL	
.XXX ±	.XXX ° ±		ASAA82*-H4RB5-*H	TITLE: CUSTOMER DRAWING 260PIN SODDR4 4.0 REV.	
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			QTY	CHKD: W.J.TANG	 SCALE SHEET REV. N/A 3/7 B
				DRAW: D.M.YANG 2018/4/18	

SOLIDWORKS GENERATED DRAWING, DO NOT CHANGE BY HAND

REV.	ECN. NO.	APPD.

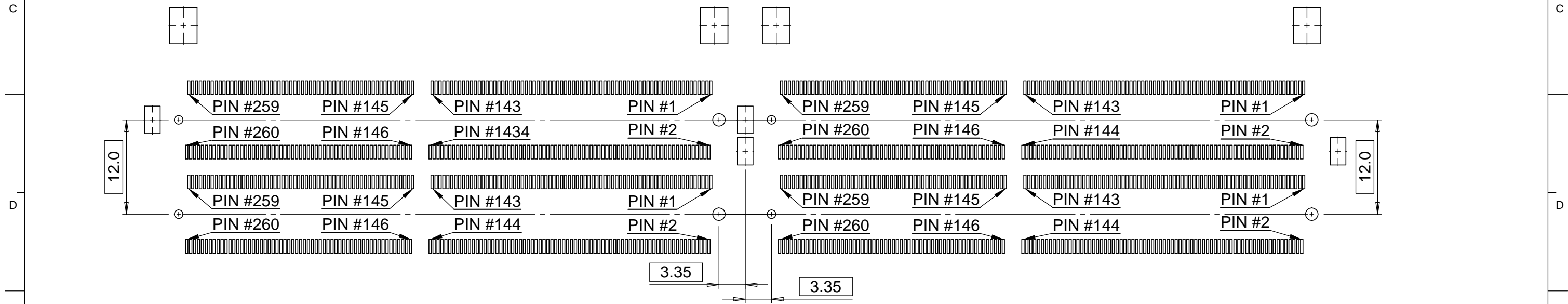
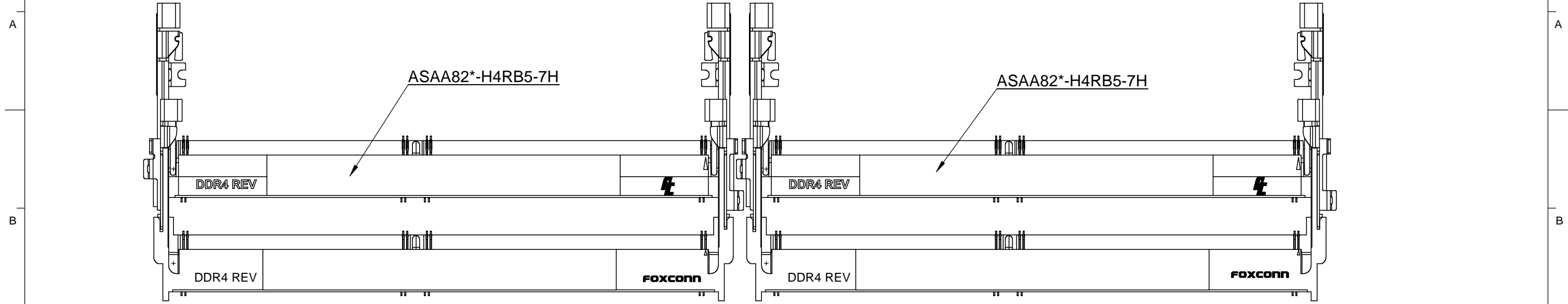


P.C.B. LAYOUT(STACKED ORIENTATION)


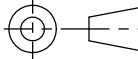
X. ± 0.25	X. °	UNITS mm	NAME (INTENDED USE)	 FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X ± 0.10	.X °		MAT'L	
.XX ± 0.05	.XX °	FINISH	PART NO. (INTENDED USE)	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
.XXX ±	.XXX °		ASAA82*-H4RB5-*H	TITLE: CUSTOMER DRAWING 260PIN SODDR4 4.0 REV.
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			CHKD: W.J.TANG	 SCALE SHEET REV. N/A 4/7 B
			DRAW: D.M.YAMG 2018/4/18	

SOLIDWORKS GENERATED DRAWING, DO NOT CHANGE BY HAND

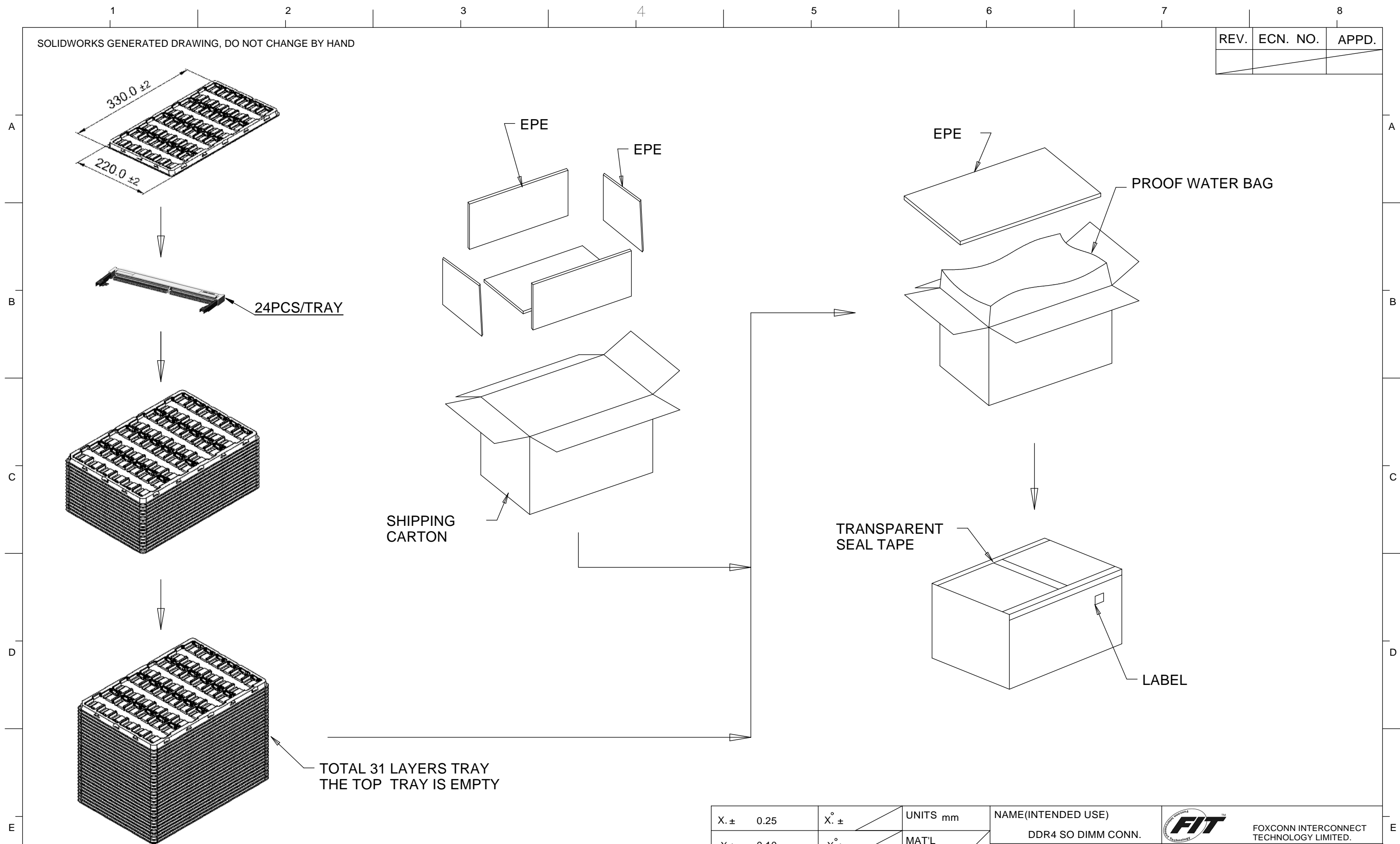
REV.	ECN. NO.	APPD.



P.C.B. LAYOUT(DUAL COMPRESSED STACKED ORIENTATION)


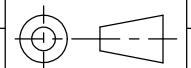
X.± 0.25	X° ±	UNITS mm	NAME (INTENDED USE)	 FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X ± 0.10	.X° ±		DDR4 SO DIMM CONN.	
.XX ± 0.05	.XX° ±	FINISH	PART NO. (INTENDED USE)	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
.XXX ±	.XXX° ±		ASAA82*-H4RB5-*H	TITLE: CUSTOMER DRAWING 260PIN SODDDR4 4.0 REV.
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			CHKD: W.J.YANG	SCALE SHEET REV.
			DRAW: D.M.YANG 2018/4/18	N/A 5/7 B
				

REV.	ECN. NO.	APPD.



NOTES:  
 1. PACKING CAPACITY : 24 PCS/TRAY, 30 TRAYS/BOX,  
 TOTAL 720 PCS/BOX.

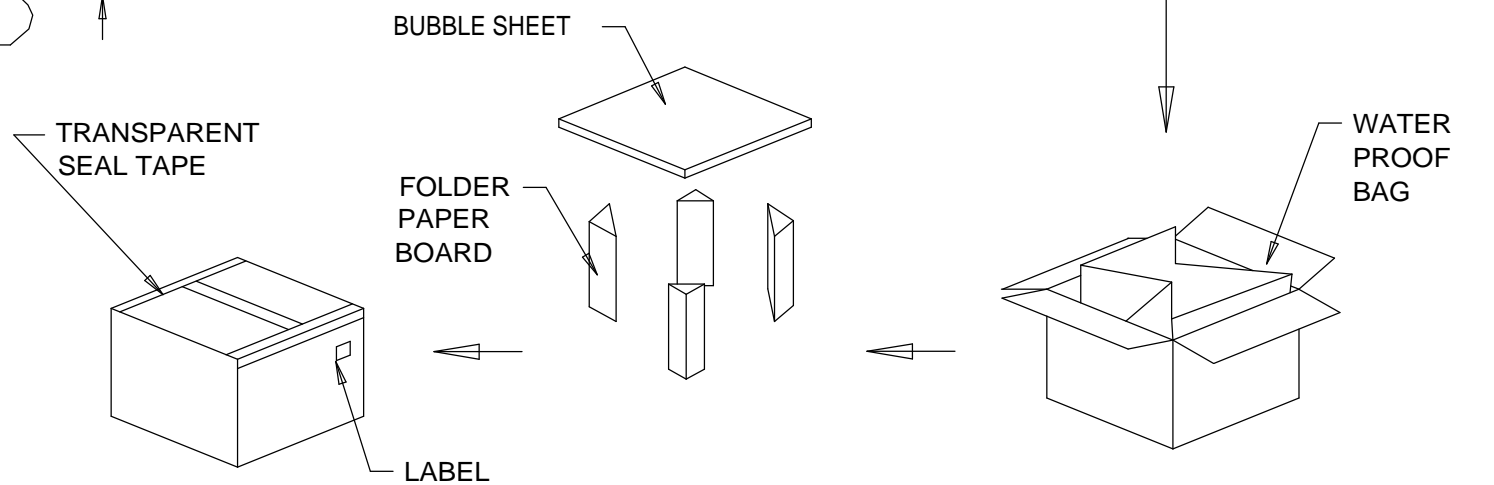
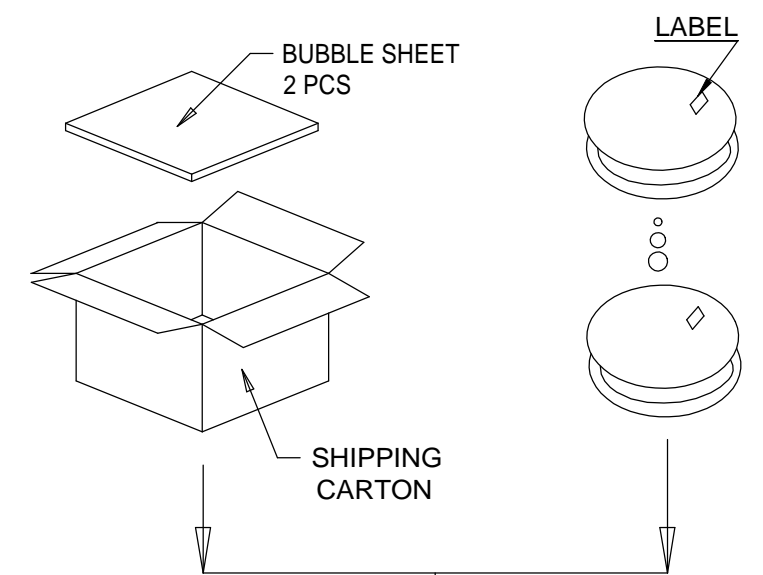
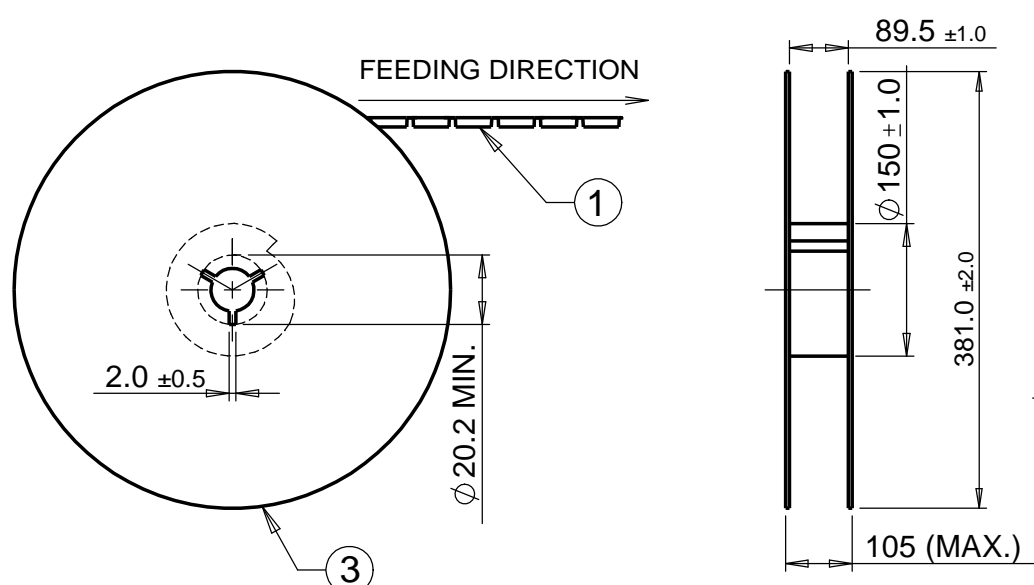
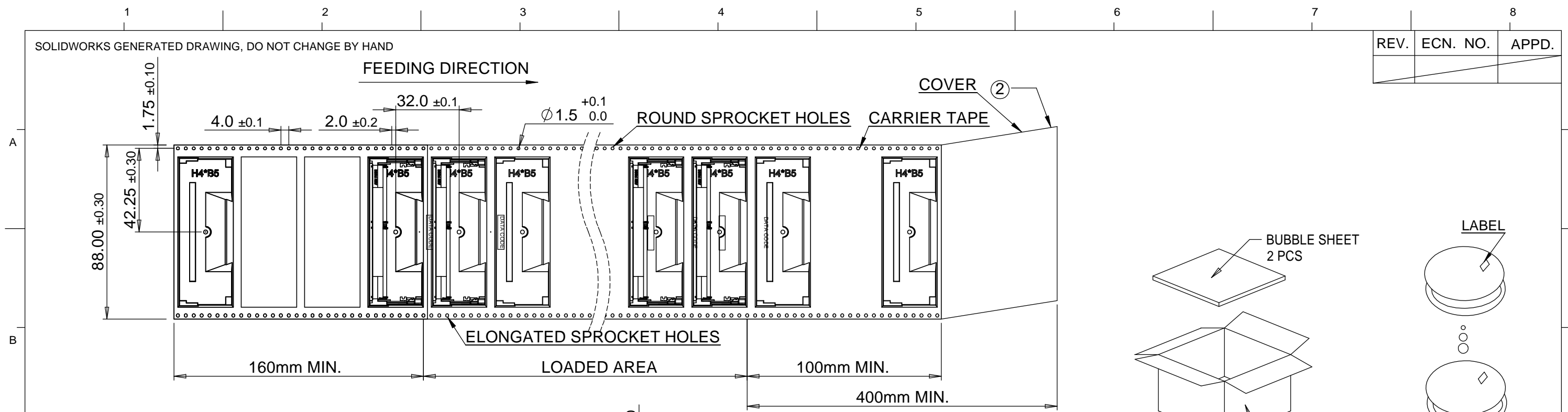
TOTAL 31 LAYERS TRAY  
 THE TOP TRAY IS EMPTY

X. ± 0.25	X. °	UNITS mm	NAME (INTENDED USE)	 FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X ± 0.10	.X °	MAT'L	DDR4 SO DIMM CONN.	
.XX ± 0.05	.XX °	FINISH	PART NO. (INTENDED USE)	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
.XXX ±	.XXX °		Q'TY	ASAA82*-H4RB5-*H
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			CHKD: W.J.TANG	 SCALE SHEET REV. N/A 6/7 B
			DRAW: D.M.YANG 2018/4/18	

CONNECTOR P/N ASAA82\*-H4RB5-4H

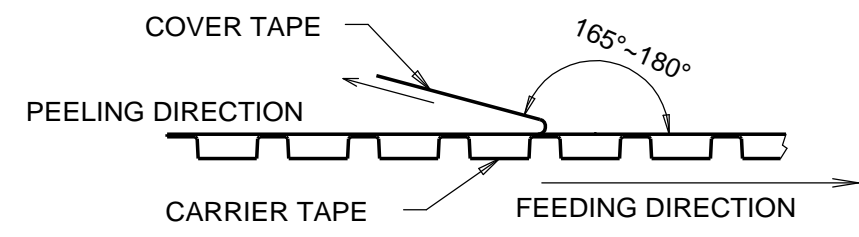
SOLIDWORKS GENERATED DRAWING, DO NOT CHANGE BY HAND

REV.	ECN. NO.	APPD.



NOTES:

- 10 POKETS HOLE PITCH CUMULATIVE TOLERANCE  $\pm 0.20\text{mm}$ .
- COVER TAPE PEELING STRENGTH : 0.01 kgf MIN & 0.15 kgf MAX. AT 300mm/min.



3. PACKING CAPACITY : 340 PCS/REEL, 3 REELS/BOX, TOTAL 1020 PCS/BOX.

3	REEL	POLYSTYRENE
2	COVER TAPE	POLYESTER
1	CARRIER TAPE	POLYSTYRENE
ITEM	DESCRIPTION	MATERIAL

X. ± 1.5	X. °	UNITS mm	NAME (INTENDED USE)	FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X ± 1.0	.X °	MAT'L	DDR4 SO DIMM CONN.	
.XX ± 0.2	.XX °	FINISH	PART NO. (INTENDED USE)	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
.XXX ±	.XXX °		ASAA82*-H4RB5-*H	TITLE: CUSTOMER DRAWING 260PIN SODDR4 4.0 REV.
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			CHKD: W.J.TANG	SCALE SHEET REV. N/A 7/7 B
			DRAW: D.M.YANG 2018/4/18	

CONNECTOR P/N ASAA82\*-H4RB5-7H